

WHAT IS CLAIMED IS:

- 1 1. A method for finding disconnection of a conductive wire formed on a
2 plate glass, the method comprising the steps of:
3 (a) applying a voltage to the conductive wire; and
4 (b) imaging thermal radiation from a surface of the conductive wire
5 by an infrared image sensor, while the step (a) is conducted, thereby
6 producing a temperature distribution image.
- 1 2. A method according to claim 1, wherein the temperature distribution
2 image is subjected to a binarization by an image processor.
- 1 3. A method according to claim 1, wherein the temperature distribution
2 image is compared with a data representing a pattern of the conductive
3 wire.
- 1 4. A method according to claim 3, wherein the data is a first image
2 data obtained by drafting the pattern of the conductive wire.
- 1 5. A method according to claim 3, wherein the data is a second image
2 data obtained, prior to the step (a), by imaging thermal radiation from the
3 surface of the conductive wire by the infrared image sensor.
- 1 6. A method according to claim 3, wherein the comparison is conducted
2 by superimposing the temperature distribution image on the data.
- 1 7. A method according to claim 3, wherein the comparison is conducted
2 by an image data subtraction between the temperature distribution image
3 and the data.

1 8. An apparatus for finding disconnection of a conductive wire formed
2 on a plate glass, the apparatus comprising:
3 a power source for applying a voltage to the conductive wire; and
4 an infrared image sensor for imaging thermal radiation from a
5 surface of the conductive wire, thereby producing a temperature distribution
6 image.

1 9. An apparatus according to claim 8, wherein the infrared image
2 sensor is an infrared camera.